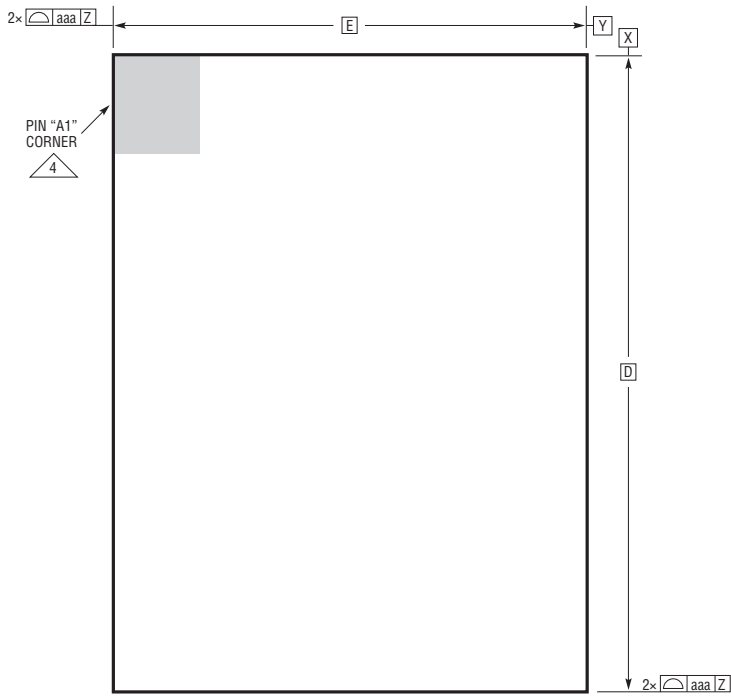
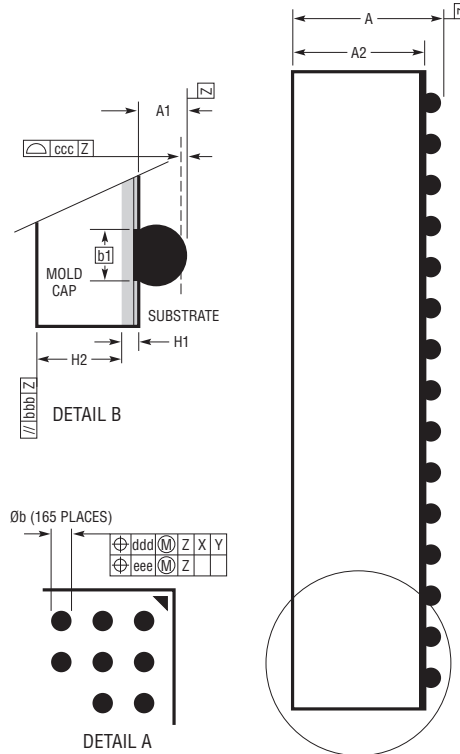


BGA Package
165-Lead (16mm × 11.9mm × 3.32mm)
 (Reference LTC DWG# 05-08-1605 Rev 0)

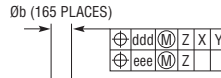


PACKAGE TOP VIEW



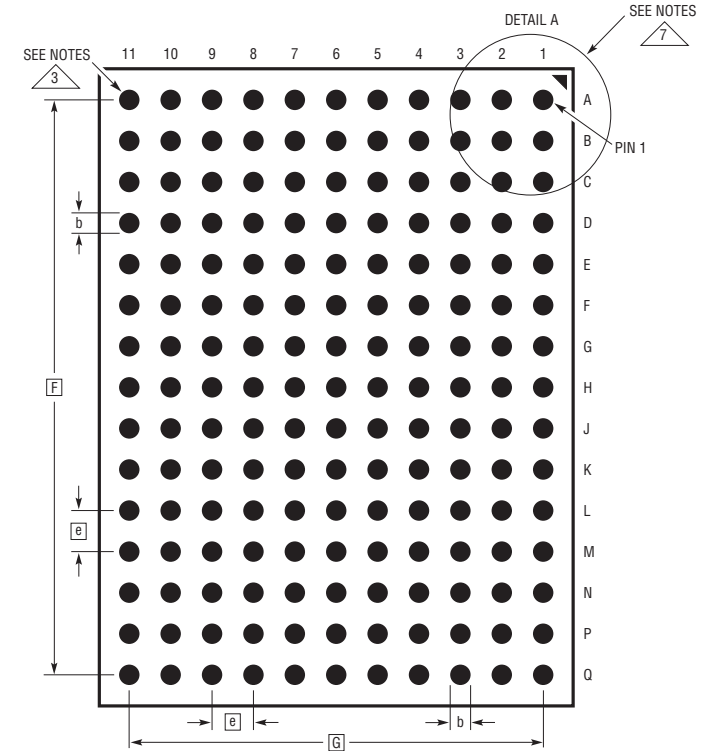
DETAIL A

DETAIL B
PACKAGE SIDE VIEW

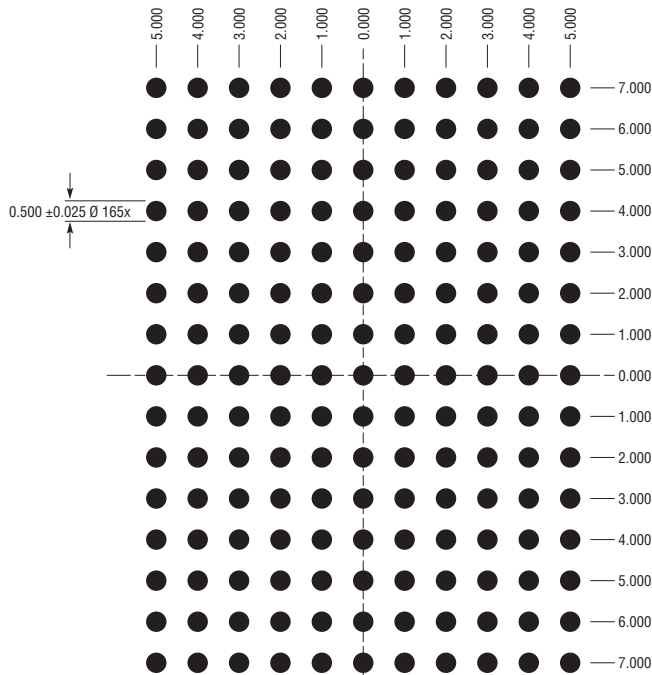


DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.13	3.32	3.51	
A1	0.40	0.50	0.60	BALL HT
A2	2.73	2.82	2.91	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D		16.00		
E		11.90		
e		1.00		
F		14.00		
G		10.00		
H1		0.32		SUBSTRATE THK
H2		2.50		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	

TOTAL NUMBER OF BALLS: 165



PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

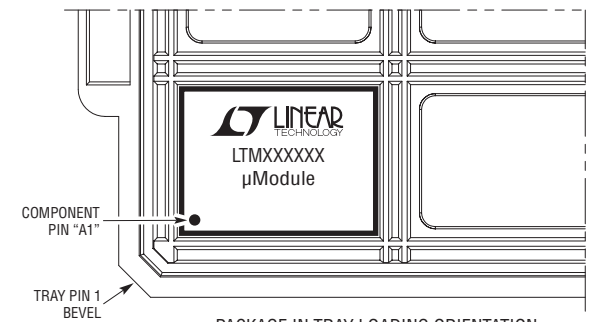
2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION